

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A film-like article comprising:
a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article, the thin film integrated circuit comprising a thin film transistor having a semiconductor film of thickness of 0.2 μm or less; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit and the antenna are mounted inside the film-like article.
2. (Currently Amended) A film-like article comprising:
a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit is mounted inside the film-like article, and the antenna is mounted on a surface of the film-like article.
3. (Currently Amended) A film-like article according to Claim 1,
wherein when the thickness of the film-like article is D, ~~the position~~ a position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2) \cdot D - 30 \mu\text{m} < X < (1/2) \cdot D + 30 \mu\text{m}$.
4. (Currently Amended) A film-like article according to Claim 2,

wherein when the thickness of the film-like article is D, ~~the position~~ a position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2) \cdot D - 30 \mu\text{m} < X < (1/2) \cdot D + 30 \mu\text{m}$.

5. (Currently Amended) A film-like article comprising:
a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit and the antenna are mounted on a surface of the film-like article.

6. (Currently Amended) A film-like article comprising:
a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit is mounted on a surface of the film-like article, and
the antenna is mounted inside the film-like article.

7. (Currently Amended) A film-like article comprising a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article, the thin film integrated circuit comprising a thin film transistor having a semiconductor film of thickness of $0.2 \mu\text{m}$ or less,
wherein the film-like article is provided with a depression, and
the thin film integrated circuit includes an antenna.

8. (Currently Amended) A film-like article according to Claim 1, further comprising

a substrate.

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate.

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

9. (Currently Amended) A film-like article according to Claim 2, further comprising

a substrate.

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate.

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

10. (Currently Amended) A film-like article according to Claim 5, further comprising:

a substrate.

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate.

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

11. (Currently Amended) A film-like article according to Claim 6, further comprising:

a substrate.

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate.

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

12. (Currently Amended) A film-like article according to Claim 7, further comprising:

a substrate,

~~wherein an opening with slits is provided in a connection area between the thin film integrated circuit and the antenna;~~ the substrate.

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

13. (Original) A film-like article according Claim 1,
wherein the thin film integrated circuit has light-transmitting characteristic.

14. (Original) A film-like article according Claim 2,
wherein the thin film integrated circuit has light-transmitting characteristic.

15. (Original) A film-like article according Claim 5,
wherein the thin film integrated circuit has light-transmitting characteristic.

16. (Original) A film-like article according Claim 6,
wherein the thin film integrated circuit has light-transmitting characteristic.

17. (Original) A film-like article according Claim 7,
wherein the thin film integrated circuit has light-transmitting characteristic.

18. (Original) A film-like article according to Claim 1,
wherein the thin film integrated circuit has an insulating film containing nitrogen.

19. (Original) A film-like article according to Claim 2,
wherein the thin film integrated circuit has an insulating film containing nitrogen.
20. (Original) A film-like article according to Claim 5,
wherein the thin film integrated circuit has an insulating film containing nitrogen.
21. (Original) A film-like article according to Claim 6,
wherein the thin film integrated circuit has an insulating film containing nitrogen.
22. (Original) A film-like article according to Claim 7,
wherein the thin film integrated circuit has an insulating film containing nitrogen.
23. (Original) A film-like article according to Claim 1,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .
24. (Original) A film-like article according to Claim 2,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .
25. (Original) A film-like article according to Claim 5,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .
26. (Original) A film-like article according to Claim 6,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

27. (Original) A film-like article according to Claim 7,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .
28. (Original) A film-like article according to Claim 1,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/ cm^3 to 5×10^{20} atoms/ cm^3 .
29. (Original) A film-like article according to Claim 2,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/ cm^3 to 5×10^{20} atoms/ cm^3 .
30. (Original) A film-like article according to Claim 5,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/ cm^3 to 5×10^{20} atoms/ cm^3 .
31. (Original) A film-like article according to Claim 6,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/ cm^3 to 5×10^{20} atoms/ cm^3 .
32. (Original) A film-like article according to Claim 7,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/ cm^3 to 5×10^{20} atoms/ cm^3 .
33. (Original) A film-like article according to any one of Claims 28 to 32,
wherein the semiconductor film includes a source, a drain, and a channel region,
and

the source, the drain, and the channel region are provided perpendicular to direction of bending the film-like article.

34. (Original) A film-like article according to Claim 1,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and
the plurality of thin film integrated circuits are integrated with antennas.

35. (Original) A film-like article according to Claim 2,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and
the plurality of thin film integrated circuits are integrated with antennas.

36. (Original) A film-like article according to Claim 5,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and
the plurality of thin film integrated circuits are integrated with antennas.

37. (Original) A film-like article according to Claim 6,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and
the plurality of thin film integrated circuits are integrated with antennas.

38. (Original) A film-like article according to Claim 7,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and
the plurality of thin film integrated circuits are integrated with antennas.

39. (Original) A film-like article according to Claim 1,
wherein the film-like article is a business card.

40. (Original) A film-like article according to Claim 2,
wherein the film-like article is a business card.

41. (Original) A film-like article according to Claim 5,
wherein the film-like article is a business card.

42. (Original) A film-like article according to Claim 6,
wherein the film-like article is a business card.

43. (Original) A film-like article according to Claim 7,
wherein the film-like article is a business card.

44. (Currently Amended) A method for manufacturing a film-like article,
comprising the steps of:
forming a plurality of thin film integrated circuits over a first substrate;
transferring the plurality of thin film integrated circuits to a second substrate;
cutting the second substrate to cut out each of the plurality of thin film integrated
circuits;
connecting an antenna to a connection terminal of the thin film integrated circuits
circuit; and
enfolding the thin film integrated circuits and the antenna in a base member of
the film-like article article.
wherein each of the plurality of the thin film integrated circuits comprises a thin
film transistor having a semiconductor film of thickness of 0.2 μm or less.

45. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;
transferring the plurality of thin film integrated circuits to a second substrate;
cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated circuits circuit; and

mounting the thin film integrated circuits and the antenna on a surface of a base member of the film-like article.

46. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;
transferring the plurality of thin film integrated circuits to a second substrate;
cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated circuits circuit; and

mounting the thin film integrated circuits and the antenna in a depression on a surface of a base member of the film-like article article.

wherein each of the plurality of the thin film integrated circuits comprises a thin film transistor having a semiconductor film of thickness of 0.2 μm or less.

47. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;
transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated circuits; and

~~enfoldng the thin film integrated circuit~~ each of the plurality of thin film integrated circuits in a base member of the film-like article,

forming an antenna on a surface of the base member of the film-like article so that the thin film integrated circuits circuit and the antenna are connected through an opening formed on the base member of the film-like article.

48. (Currently Amended) A method for manufacturing a film-like article, comprising the step of forming an antenna on a surface of a base member of the film-like article so that a plurality of thin film integrated circuits and the antenna are connected through an opening formed on the base member of the film-like article,

wherein ~~[[a]]~~ the plurality of thin film integrated circuits are formed over a first substrate,

the plurality of thin film integrated circuits are transferred to a second substrate, and

the second substrate is cut so as to cut out the plurality of thin film integrated circuits circuits.

wherein each of the plurality of the thin film integrated circuits comprises a thin film transistor having a semiconductor film of thickness of 0.2 μ m or less.